DOCUMENT CHANGE REQUEST

DCR number 572	Changes required for: MRB decision	Originator: Padraic Moran
Date: 2010/02/03	Date sent: 2010/02/03	Organisation: Enterprise Ireland
Status: IMPLEMENTED		

Title:	Thermistors (Thermally Sensitive Resistors) Range 1000 to 10000 Ohms at +25C with a Temperature		
Number:	4006/013	Issue:	5

Other documents affected:

Page:

Addition of:
Page 15, APPENDIX 'A'

Paragraph:

Addition of:
Page 15, APPENDIX 'A'

Original wording:

Proposed wording:

See attached doc:
ESCC 4006013 proposed changes.pdf

Justification:

See attached doc:
ESCC 4006013 proposed changes.pdf

Attachments:

ESCC_4006013_proposed_changes.pdf, null

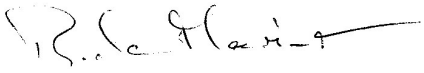
Modifications:

Amend the attachment to DCR572 as follows:
a) The Manufacturer's name used for Appendix 'A' shall remain as 'Betatherm (Ireland)'.

b) Replace the text in the DESCRIPTION OF DEVIATIONS column of Appendix 'A' (applicable to all items) to read as follows:

Para. 9.3.1.4, Insulation Resistance
Insulation Resistance may be measured in accordance with Betatherm Specification Ref. MFG 12-49-00.

Approval signature:



Date signed:
2010-02-03

ADDITION OF:

APPENDIX 'A'

AGREED DEVIATIONS FOR MEAS IRELAND (BETATHERM) LTD.

ITEMS AFFECTED	DESCRIPTION OF DEVIATIONS
Para. 4.2.2 Deviations from Final Production Tests (Chart II)	Para. 9.3.1.4 Insulation Resistance The following applies to Variants 01, 02, 03, 04, 05, 06 & 07: Section (b) Special Preparations of para. 9.3.1.4 does not apply. Section (c) Points of Measurement of para. 9.3.1.4 excludes reference to the V-Block. The word 'V-Block' is replaced by the words 'body of the thermistor' Insulation Resistance test method is as per agreed specification # MFG 12-49-00.
Para. 4.2.3 Deviations from Burn-in and Electrical Measurements (Chart III)	
Para. 4.2.4 Deviation from Qualification Tests (Chart IV)	
Para. 4.2.5 Deviations from Lot Acceptance Tests (Chart V)	

JUSTIFICATION:

1. The use of the V-Block is not optimal for the testing of ESCC 4006/013 type devices with respect to issues such as clamping of the device and also contact to non-conductive surfaces of the device. The proposed method as per MFG 12-49-00 uses solder balls to surround the device enabling all surfaces to always have good contact with the solder balls.